



**Applied Materials Mirra
Integra
Poly/STI CMP
Serial Number L358**

**Currently Configured for 200mm wafer
size MFG Date: 1999**

EQUIPMENT DETAILS:

- Wafer Size (inches) : 8
- Install Type : Through-the-wall
- Year of Manufacture: 1999
- Software Version : MB59c3
- CPU Board Type :
Pentium 3 400MHz or
Higher : Yes
- Electrical Requirements : 200/208VAC
- Process Type: Polysilicon
- Mainframe: Mirra
- Track o Dry In/Dry Out
- o Signal Lamp Tower
- o Integrated SMIF (qty 3 loaders)
- o Cassette Tank : Standard
- o Robot Type : 112"
- o Cleaner Type : Ontrak
- o Cleaner Chemicals Used : CP72
- o E-Chain Lifetime : Since installation
- o Cleaning Package : No
- o Spray Gun : Single
- o In-Situ Removal Rate Monitor : Motor Torque
- o Metrology Option : None
- o IPM : No
- Mirra Polish
- Heads o Titan 1
- Polish Heads



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- o PPS Retaining Rings
- o Standard Wafer Loss Sensor
 - Mirra Platens
- o Teflon Coated Platens : No
- o Pad Type : IC 1000
- o Pad Conditioner Head : P4
Intel
- o Pad Conditioner Disc : EWHA
- o Universal Disk Holder : No
- o Temperature Control : None
 - Slurries
- o Slurries/Platen Used : 1
- o Chemicals Used : Oxide Slurry
- o Flow Rate : Standard
- o Dispense Arm : Standard
- o Slurry Flow Monitors : Yes





